



ELECTRONICS, INC.
 44 FARRAND STREET
 BLOOMFIELD, NJ 07003
 (973) 748-5089
<http://www.nteinc.com>



NTE622

Silicon Rectifier, General Purpose, High Voltage, Fast Recovery

DO-213AA Surface Mount Type Case

Features:

- High Temperature Metallurgically Bonded
- Glass Passivated Junction
- High Temperature Soldering Guaranteed:
 +450°C/5 Seconds at Terminals. Complete Device Submersible Temperature of
 +260°C/10 Seconds in Solder Bath.

Maximum Ratings and Electrical Characteristics: ($T_A = +25^\circ\text{C}$ unless otherwise specified.
 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.)

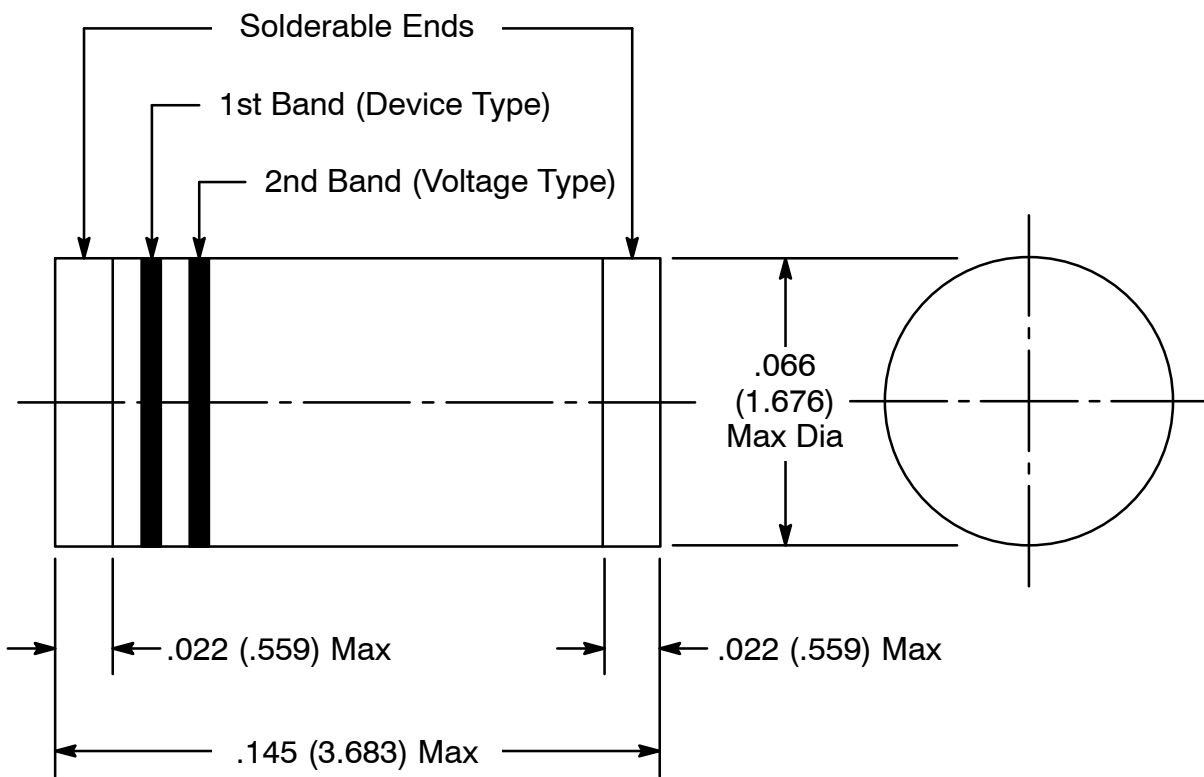
Maximum Recurrent Peak Reverse Voltage, V_{RRM}	400V
Maximum RMS Voltage, V_{RMS}	280V
Maximum DC Blocking Voltage, V_{DC}	400V
Maximum Average Forward Rectified Current ($T_T = +75^\circ\text{C}$), $I_{T(AV)}$	0.5A
Peak Forward Surge Current, I_{FSM} (8.3ms Single Half Sine-Wave Superimposed on Rated Load)	10A
Maximum Instantaneous Forward Voltage ($I_T = 0.5A$), V_F	1.2V
Maximum DC Reverse Current ($V_{DC} = 400V$), I_R	
$T_A = +25^\circ\text{C}$	5 μ A
$T_A = +125^\circ\text{C}$	50 μ A
Maximum Reverse Recovery Time ($T_J = +25^\circ\text{C}$, Note 1), t_{rr}	50ns
Typical Junction Capacitance (Note 2), C_J	4pF
Operating Junction Temperature Range, T_J	-65° to +175°C
Storage Temperature Range, T_{stg}	-65° to +175°C
Maximum Thermal Resistance, Junction-to-Terminal (Note 3), R_{thJL}	70°C/W
Maximum Thermal Resistance, Junction-to-Ambient (Note 4), R_{thJA}	150°C/W

Note 1. Reverse Recovery Test Conditions: $I_F = 0.5A$, $I_R = 1A$, $I_{RR} = 0.25A$..

Note 2. Measured at 1MHz and applied reverse voltage of $4V_{DC}$.

Note 2. Thermal resistance, junction-to-terminal, 5.0mm² copper pads to each terminal.

Note 3. Thermal resistance, junction-to-ambient, 5.0mm² copper pads to each terminal.



Two Bands Indicates Cathode